Renesas Electronics America Inc - R5F2L38CCNFA#V1 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	LCD, POR, PWM, Voltage Detect, WDT
Number of I/O	68
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 16x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2l38ccnfa-v1

Table 1.2 Programmable I/O Ports Provided for Each Group

Programmable I/O Port	R8C/L35C Group Total: 41 I/O pins								R8C/L36C Group Total: 52 I/O pins								R8C/L38C Group Total: 68 I/O pins								R8C/L3AC Group Total: 88 I/O pins							
	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
P0	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P1	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P2	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P3	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P4	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P5	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	✓	✓	✓	✓
P6	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P7	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P10	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓
P11	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P12	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓
P13	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓

Notes:
1. The symbol "✓" indicates a programmable I/O port.
2. The symbol "–" indicates the settings should be made as follows:
   - Set 1 to the corresponding bits in the PDi (i = 1 to 3, 5 to 7, and 10 to 13) register.
   - Set 0 to the corresponding bits in the Pi (i = 1 to 3, 5 to 7, and 10 to 13) register.
   - Set 0 to the corresponding bits in the P10DRR or P11DRR register.

Table 1.3 LCD Display Function Pins Provided for Each Group

Shared I/O Port	L35C Group Common output: Max. 4 Segment output: Max. 24								L36C Group Common output: Max. 8 Segment output: Max. 32								L38C Group Common output: Max. 8 Segment output: Max. 48								L3AC Group Common output: Max. 8 Segment output: Max. 56							
P0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0
P1	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	SEG 11	SEG 10	SEG 9	SEG 8	SEG 15	SEG 14	SEG 13	SEG 12	SEG 11	SEG 10	SEG 9	SEG 8
P2	SEG 23	SEG 22	SEG 21	SEG 20	–	–	–	–	SEG 23	SEG 22	SEG 21	SEG 20	–	–	–	–	SEG 23	SEG 22	SEG 21	SEG 20	SEG 19	SEG 18	SEG 17	SEG 16	SEG 23	SEG 22	SEG 21	SEG 20	SEG 19	SEG 18	SEG 17	SEG 16
P3	–	–	–	–	SEG 27	SEG 26	SEG 25	SEG 24	SEG 31	SEG 30	SEG 29	SEG 28	SEG 27	SEG 26	SEG 25	SEG 24	SEG 31	SEG 30	SEG 29	SEG 28	SEG 27	SEG 26	SEG 25	SEG 24	SEG 31	SEG 30	SEG 29	SEG 28	SEG 27	SEG 26	SEG 25	SEG 24
P4	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32
P5	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	SEG 43	SEG 42	SEG 41	SEG 40
P6	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	SEG 51	SEG 50	SEG 49	SEG 48	SEG 47	SEG 46	SEG 45	SEG 44	SEG 51	SEG 50	SEG 49	SEG 48	SEG 47	SEG 46	SEG 45	SEG 44
P7	COM 0	COM 1	COM 2	COM 3	–	–	–	–	COM 0	COM 1	COM 2	COM 3	SEG 55	SEG 54	SEG 53	SEG 52	COM 0	COM 1	COM 2	COM 3	SEG 55	SEG 54	SEG 53	SEG 52	COM 0	COM 1	COM 2	COM 3	SEG 55	SEG 54	SEG 53	SEG 52
P12	–	–	–	–	CL2	CL1	–	–	–	–	–	–	CL2	CL1	–	–	–	–	–	–	CL2	CL1	–	–	–	–	–	–	CL2	CL1	–	–
–	VL1								VL1								VL1								VL1							
–	VL2								VL2								VL2								VL2							
–	–								VL3								VL3								VL3							
–	VL4								VL4								VL4								VL4							

Notes:
1. The symbol "–" indicates there is no LCD display function. Set the corresponding bits in registers LSE1 to LSE3, LSE5 to LSE7 to 0 for these pins.
2. SEG52 to SEG55 can be used as COM7 to COM4.
   The R8C/L35C Group does not have pins SEG52 to SEG55, so 1/8 duty cannot be selected.
3. The R8C/L35C Group does not have the VL3 pin, so 1/4 bias cannot be selected. When the internal voltage multiplier is used, 1/2 bias cannot also be selected.

Table 1.6 Specifications (3)

Item	Specification
Flash Memory	• Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 10,000 times (data flash) 1,000 times (program ROM) • Program security: ROM code protect, ID code check • On-chip debug function • On-board flash rewrite function • Background operation (BGO) function
Operating Frequency/ Supply Voltage	f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 1.8 to 5.5 V)
Current Consumption	Typ. 7 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 3.6 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 3.5 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) Typ. 2 μA (VCC = 3.0 V, stop mode) Typ. 0.02 μA (VCC = 3.0 V, power-off mode)
Operating Ambient Temperature	-20 to 85°C (N version) -40 to 85°C (D version) (1)

Note:
1. Specify the D version if D version functions are to be used.

1.2 Product Lists

Tables 1.7 to 1.10 list Product List for Each Group. Figures 1.1 to 1.4 show the Correspondence of Part No., with Memory Size and Package for Each Group.

Table 1.7 Product List for R8C/L35C Group **Current of Apr 2011**

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F2L357CNFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0052JA-A	N Version
R5F2L358CNFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0052JA-A	
R5F2L35ACNFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0052JA-A	
R5F2L35CCNFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0052JA-A	
R5F2L357CDFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0052JA-A	D Version
R5F2L358CDFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0052JA-A	
R5F2L35ACDFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0052JA-A	
R5F2L35CCDFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0052JA-A	

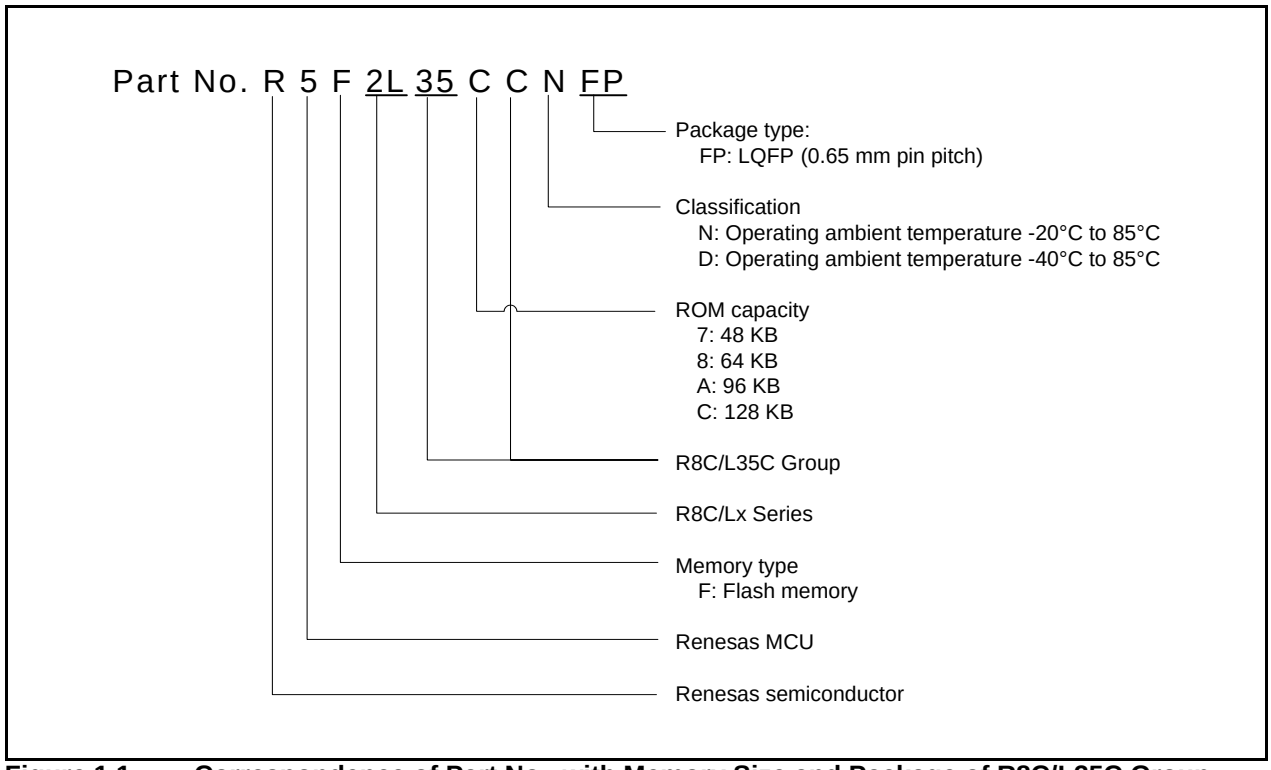


Figure 1.1 Correspondence of Part No., with Memory Size and Package of R8C/L35C Group

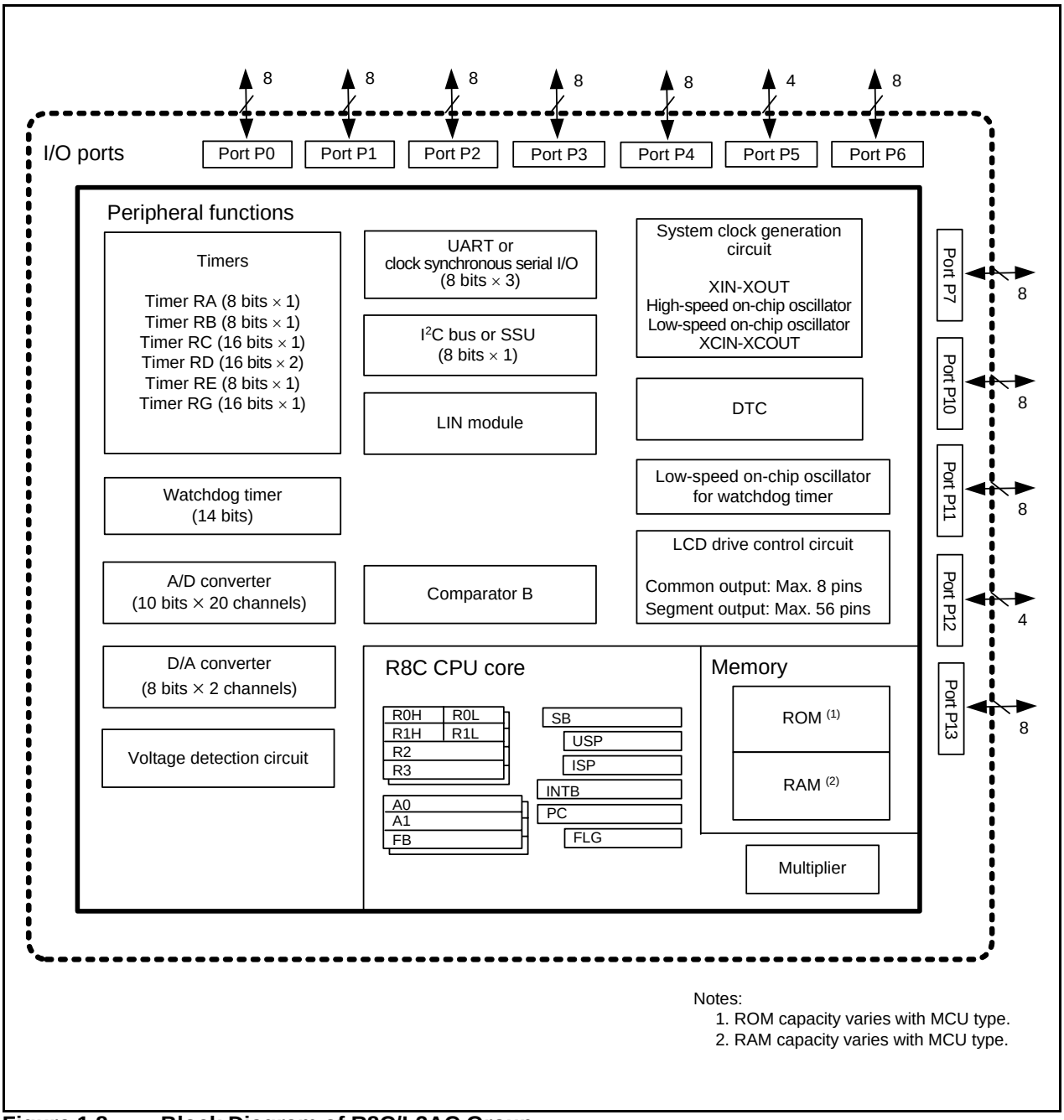


Figure 1.8 Block Diagram of R8C/L3AC Group

1.5 Pin Functions

Tables 1.14 and 1.15 list Pin Functions for R8C/L3AC Group.

Table 1.14 Pin Functions for R8C/L3AC Group (1)

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	–	Apply 1.8 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	–	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Driving this pin low resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
Power-off mode exit input	$\overline{\text{WKUP0}}$	I	This pin is provided for input to exit the mode used in power-off mode. Connect to VSS when not using power-off mode.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic oscillator or a crystal oscillator between pins XIN and XOUT. (1) To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XIN clock output	XOUT	O	
XCIN clock input	XCIN	I	These pins are provided for XCIN clock generation circuit I/O. Connect a crystal oscillator between pins XCIN and XCOUT. (1) To use an external clock, input it to the XCIN pin and leave the XCOUT pin open.
XCIN clock output	XCOUT	O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT7}}$	I	$\overline{\text{INT}}$ interrupt input pins.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI7}}$	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRAO	O	Timer RA output pin
Timer RB	TRBO	O	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
	TRCTRG	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIOC, TRCIOD	I/O	Timer RC I/O pins
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O pins
	TRDCLK	I	External clock input pin
Timer RE	TREO	O	Divided clock output pin
Timer RG	TRGCLKA, TRGCLKB	I	Timer RG input pins
	TRGIOA, TRGIOB	I/O	Timer RG I/O pins
Serial interface	CLK0, CLK1, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD1, RXD2	I	Serial data input pins
	TXD0, TXD1, TXD2	O	Serial data output pins
	$\overline{\text{CTS2}}$	I	Transmission control input pin
	$\overline{\text{RTS2}}$	O	Reception control output pin
	SCL2	I/O	I^2C mode clock I/O pin
	SDA2	I/O	I^2C mode data I/O pin

I: Input O: Output I/O: Input and output

Note:

1. Contact the oscillator manufacturer for oscillation characteristics.

Table 1.15 Pin Functions for R8C/L3AC Group (2)

Item	Pin Name	I/O Type	Description
I^2C bus	SCL	I/O	Clock I/O pin
	SDA	I/O	Data I/O pin
SSU	SSI	I/O	Data I/O pin
	$\overline{SCS}$	I/O	Chip-select signal I/O pin
	SSCK	I/O	Clock I/O pin
	SSO	I/O	Data I/O pin
Reference voltage input	VREF	I	Reference voltage input pin for the A/D converter and the D/A converter
A/D converter	AN0 to AN11	I	A/D converter analog input pins
	$\overline{ADTRG}$	I	A/D external trigger input pin
D/A converter	DA0, DA1	O	D/A converter output pins
Comparator B	IVCMP1, IVCMP3	I	Comparator B analog voltage input pins
	IVREF1, IVREF3	I	Comparator B reference voltage input pins
I/O ports	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0, P5_3, P6_0 to P6_7 P7_0 to P7_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_3, P13_0 to P13_7	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. Ports P10_0 to P10_7 and P11_0 to P11_7 can be used as LED drive ports.
Segment output	SEG0 to SEG55	O	LCD segment output pins
Common output	COM0 to COM7	O	LCD common output pins
Voltage multiplier capacity connect pins	CL1, CL2	O	Connect pins for the LCD control voltage multiplier
LCD power supply	VL1	I/O	Apply the voltage: $0 \leq VL1 \leq VL2 \leq VL3 \leq VL4$. VL1 can be used as the reference potential input or output pin when setting the voltage multiplier.
	VL2 to VL4	I	

I: Input O: Output I/O: Input and output

Note:

1. Contact the oscillator manufacturer for oscillation characteristics.

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.
Interrupts are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.
The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

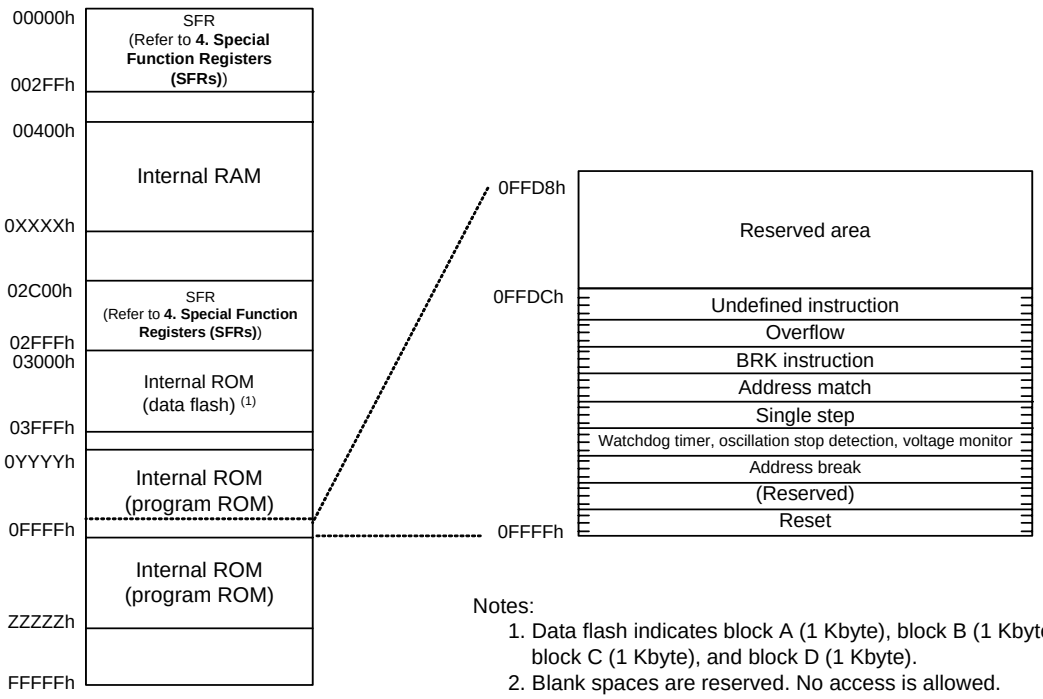
IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7.
If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

3. Memory

Figure 3.1 is a Memory Map of each group. Each group has a 1-Mbyte address space from addresses 00000h to FFFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.
The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.
The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 6-Kbyte internal RAM area is allocated addresses 00400h to 01BFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh. Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.



Notes:
1. Data flash indicates block A (1 Kbyte), block B (1 Kbyte), block C (1 Kbyte), and block D (1 Kbyte).
2. Blank spaces are reserved. No access is allowed.

Part Number	Internal ROM			Internal RAM	
	Capacity	Address 0YYYYh	Address ZZZZZh	Capacity	Address 0XXXXh
R5F2L357C***, R5F2L367C***, R5F2L387C***, R5F2L3A7C***	48 Kbytes	04000h	–	6 Kbytes	01BFFh
R5F2L358C***, R5F2L368C***, R5F2L388C***, R5F2L3A8C***	64 Kbytes	04000h	13FFFh	8 Kbytes	023FFh
R5F2L35AC***, R5F2L36AC***, R5F2L38AC***, R5F2L3AAC***	96 Kbytes	04000h	1BFFFh	10 Kbytes	02BFFh
R5F2L35CC***, R5F2L36CC***, R5F2L38CC***, R5F2L3ACC***	128 Kbytes	04000h	23FFFh	10 Kbytes	02BFFh

Figure 3.1 Memory Map

4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.16 list SFR Informations and Table 4.17 lists the ID Code Areas and Option Function Select Area. The description offered in this chapter is based on the R8C/L3AC Group.

Table 4.1 SFR Information (1) (1)

Address	Register	Symbol	After Reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	00100000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h	Module Standby Control Register	MSTCR	00h
0009h	System Clock Control Register 3	CM3	00h
000Ah	Protect Register	PRCR	00h
000Bh	Reset Source Determination Register	RSTFR	XXh (2)
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDTC	00111111b
0010h			
0011h			
0012h			
0013h			
0014h			
0015h	High-Speed On-Chip Oscillator Control Register 7	FRA7	When shipping
0016h			
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h 10000000b (3)
001Dh			
001Eh			
001Fh			
0020h	Power-Off Mode Control Register 0	POMCR0	X0000000b
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h	On-Chip Reference Voltage Control Register	OCVREFCR	00h
0027h			
0028h			
0029h	High-Speed On-Chip Oscillator Control Register 4	FRA4	When Shipping
002Ah	High-Speed On-Chip Oscillator Control Register 5	FRA5	When Shipping
002Bh	High-Speed On-Chip Oscillator Control Register 6	FRA6	When Shipping
002Ch			
002Dh			
002Eh			
002Fh	High-Speed On-Chip Oscillator Control Register 3	FRA3	When shipping
0030h	Voltage Monitor Circuit Control Register	CMPA	00h
0031h	Voltage Monitor Circuit Edge Select Register	VCAC	00h
0032h			
0033h	Voltage Detect Register 1	VCA1	00001000b
0034h	Voltage Detect Register 2	VCA2	00h (4) 00100000b (5)
0035h			
0036h	Voltage Detection 1 Level Select Register	VD1LS	00000111b
0037h			
0038h	Voltage Monitor 0 Circuit Control Register	VW0C	1100X010b (4) 1100X011b (5)
0039h	Voltage Monitor 1 Circuit Control Register	VW1C	10001010b

X: Undefined

Notes:
1. Blank spaces are reserved. No access is allowed.
2. The CWR bit in the RSTFR register is set to 0 after power-on, voltage monitor 0 reset, or exit from power-off mode. Hardware reset, software reset, or watchdog timer reset does not affect this bit.
3. The CSPROINI bit in the OFS register is set to 0.
4. The LVDAS bit in the OFS register is set to 1.
5. The LVDAS bit in the OFS register is set to 0.

Table 4.10 SFR Information (10) (1)

Address	Register	Symbol	After Reset
0240h	LCD Display Data Register	LRA48L	XXh
0241h		LRA49L	XXh
0242h		LRA50L	XXh
0243h		LRA51L	XXh
0244h		LRA52L	XXh
0245h		LRA53L	XXh
0246h		LRA54L	XXh
0247h		LRA55L	XXh
0248h			
0249h			
024Ah			
024Bh			
024Ch			
024Dh			
024Eh			
024Fh			
0250h			
0251h			
0252h			
0253h			
0254h			
0255h			
0256h			
0257h			
0258h			
0259h			
025Ah			
025Bh			
025Ch			
025Dh			
025Eh			
025Fh			
0260h			
0261h			
0262h			
0263h			
0264h			
0265h			
0266h			
0267h			
0268h			
0269h			
026Ah			
026Bh			
026Ch			
026Dh			
026Eh			
026Fh			
0270h	LCD Display Control Data Register	LRA0H	XXh
0271h		LRA1H	XXh
0272h		LRA2H	XXh
0273h		LRA3H	XXh
0274h		LRA4H	XXh
0275h		LRA5H	XXh
0276h		LRA6H	XXh
0277h		LRA7H	XXh
0278h		LRA8H	XXh
0279h		LRA9H	XXh
027Ah		LRA10H	XXh
027Bh		LRA11H	XXh
027Ch		LRA12H	XXh
027Dh		LRA13H	XXh
027Eh		LRA14H	XXh
027Fh		LRA15H	XXh

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

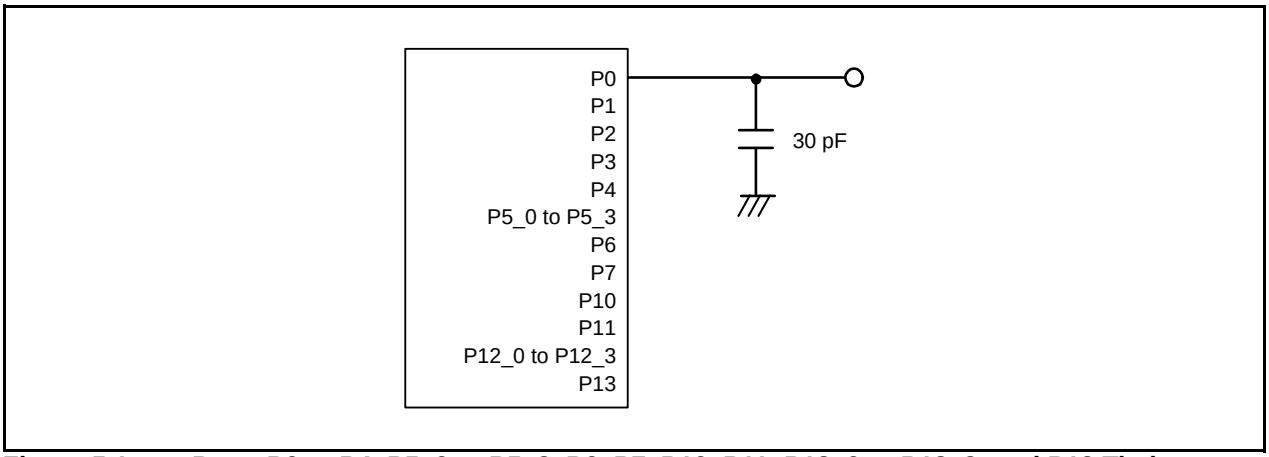


Figure 5.1 Ports P0 to P4, P5_0 to P5_3, P6, P7, P10, P11, P12_0 to P12_3, and P13 Timing Measurement Circuit

Table 5.4 D/A Converter Characteristics
(V_{CC}/AV$_{CC}$ = Vref = 2.7 to 5.5 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Resolution		—	—	8	Bit
—	Absolute accuracy		—	—	2.5	LSB
t_{su}	Setup time		—	—	3	µs
R_O	Output resistor		—	6	—	kΩ
I_{Vref}	Reference power input current	(Note 1)	—	—	1.5	mA

Note:
1. This applies when one D/A converter is used and the value of the DAi register (i = 0 or 1) for the unused D/A converter is 00h. The resistor ladder of the A/D converter is not included.

Table 5.5 Comparator B Characteristics
(V_{CC} = 2.7 to 5.5 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Vref	IVREF1, IVREF3 input reference voltage		0	—	V_{CC} – 1.4	V
V_I	IVCMP1, IVCMP3 input voltage		–0.3	—	V_{CC} + 0.3	V
—	Offset		—	5	100	mV
t_d	Comparator output delay time (1)	V_I = Vref ± 100 mV	—	0.1	—	µs
I_{CMP}	Comparator operating current	V_{CC} = 5.0 V	—	17.5	—	µA

Note:
1. When the digital filter is disabled.

Table 5.6 Flash Memory (Program ROM) Characteristics
(V_{CC} = 2.7 to 5.5 V and T_{opr} = 0 to 60°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		1,000 (2)	—	—	times
—	Byte program time		—	80	500	µs
—	Block erase time		—	0.3	—	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	ms
—	Time from suspend until erase restart		—	—	30+CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30+CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		0	—	60	°C
—	Data hold time (6)	Ambient temperature = 55°C	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.8 Voltage Detection 0 Circuit Characteristics (Vcc = 1.8 to 5.5 V and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det0}	Voltage detection level Vdet0_0 (1)		1.80	1.90	2.05	V
	Voltage detection level Vdet0_1 (1)		2.15	2.35	2.50	V
	Voltage detection level Vdet0_2 (1)		2.70	2.85	3.05	V
	Voltage detection level Vdet0_3 (1)		3.55	3.80	4.05	V
—	Voltage detection 0 circuit response time (3)	At the falling of Vcc from 5 V to (Vdet0_0 – 0.1) V	—	6	150	µs
—	Voltage detection circuit self power consumption	VCA25 = 1, Vcc = 5.0 V	—	1.5	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (2)		—	—	100	µs

Notes:
1. Select the voltage detection level with bits VDSEL0 and VDSEL1 in the OFS register.
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA25 bit in the VCA2 register to 0.
3. Time until the voltage monitor 0 reset is generated after the voltage passes V_{det0}.

Table 5.9 Voltage Detection 1 Circuit Characteristics (Vcc = 1.8 to 5.5 V and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det1}	Voltage detection level Vdet1_0 (1)	At the falling of Vcc	2.00	2.20	2.40	V
	Voltage detection level Vdet1_1 (1)	At the falling of Vcc	2.15	2.35	2.55	V
	Voltage detection level Vdet1_2 (1)	At the falling of Vcc	2.30	2.50	2.70	V
	Voltage detection level Vdet1_3 (1)	At the falling of Vcc	2.45	2.65	2.85	V
	Voltage detection level Vdet1_4 (1)	At the falling of Vcc	2.60	2.80	3.00	V
	Voltage detection level Vdet1_5 (1)	At the falling of Vcc	2.75	2.95	3.15	V
	Voltage detection level Vdet1_6 (1)	At the falling of Vcc	2.85	3.10	3.40	V
	Voltage detection level Vdet1_7 (1)	At the falling of Vcc	3.00	3.25	3.55	V
	Voltage detection level Vdet1_8 (1)	At the falling of Vcc	3.15	3.40	3.70	V
	Voltage detection level Vdet1_9 (1)	At the falling of Vcc	3.30	3.55	3.85	V
	Voltage detection level Vdet1_A (1)	At the falling of Vcc	3.45	3.70	4.00	V
	Voltage detection level Vdet1_B (1)	At the falling of Vcc	3.60	3.85	4.15	V
	Voltage detection level Vdet1_C (1)	At the falling of Vcc	3.75	4.00	4.30	V
	Voltage detection level Vdet1_D (1)	At the falling of Vcc	3.90	4.15	4.45	V
	Voltage detection level Vdet1_E (1)	At the falling of Vcc	4.05	4.30	4.60	V
	Voltage detection level Vdet1_F (1)	At the falling of Vcc	4.20	4.45	4.75	V
—	Hysteresis width at the rising of Vcc in voltage detection 1 circuit	Vdet1_0 to Vdet1_5 selected	—	0.07	—	V
		Vdet1_6 to Vdet1_F selected	—	0.10	—	V
—	Voltage detection 1 circuit response time (2)	At the falling of Vcc from 5 V to (Vdet1_0 – 0.1) V	—	60	150	µs
—	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (3)		—	—	100	µs

Notes:
1. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
2. Time until the voltage monitor 1 interrupt request is generated after the voltage passes V_{det1}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 5.15 LCD Drive Control Circuit Characteristics (VCC = 1.8 to 5.5 V, VSS = 0 V, and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
VLCD	LCD power supply voltage	VLCD = VL4	2.2	—	5.5	V
VL3	VL3 voltage		VL2	—	VL4	V
VL2	VL2 voltage	R8C/L35C	VL1	—	VL4	V
		R8C/L36C, R8C/L38C, R8C/L3AC	VL1	—	VL3	V
VL1	VL1 voltage		1	—	VL2 (3)	V
—	VL1 internally-generated voltage accuracy (1)		Setting voltage –0.2	Setting voltage	Setting voltage +0.2	V
f(FR)	Frame frequency		50	—	180	Hz
ILCD	LCD drive control circuit current		—	(Note 2)	—	µA

Notes:
1. The voltage is selected with bits LVLS0 to LVLS3 in the LCR1 register.
2. Refer to **Table 5.18 DC Characteristics (2)**, **Table 5.20 DC Characteristics (4)**, and **Table 5.22 DC Characteristics (6)**.
3. The VL1 voltage should be VCC or below.

Table 5.16 Power-Off Mode Characteristics (VCC = 2.2 to 5.5 V, VSS = 0 V, and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
—	Power-off mode operating supply voltage		2.2	—	5.5	V

Table 5.20 DC Characteristics (4) [2.7 V ≤ Vcc < 4.0 V]
(Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition								Standard			Unit
			Oscillation Circuit		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ. (3)	Max.	
			XIN (2)	XCIN	High-Speed (fOCO-F)	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	20 MHz	Off	Off	125 kHz	No division	—		—	7.0	14.5	mA
			10 MHz	Off	Off	125 kHz	No division	—		—	3.6	10	mA
			20 MHz	Off	Off	125 kHz	Divide-by-8	—		—	3.0	—	mA
			10 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.5	—	mA
		High-speed on-chip oscillator mode	Off	Off	20 MHz	125 kHz	No division	—		—	7.0	14.5	mA
			Off	Off	20 MHz	125 kHz	Divide-by-8	—		—	3.0	—	mA
			Off	Off	10 MHz	125 kHz	No division	—		—	4.0	—	mA
			Off	Off	10 MHz	125 kHz	Divide-by-8	—		—	1.7	—	mA
			Off	Off	4 MHz	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRD = 1 MSTTRC = 1 MSTTRG = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 VCA20 = 0		—	85	390	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 VCA20 = 0		—	90	400	µA
			Off	32 kHz	Off	Off	No division	FMSTP = 1 VCA20 = 0	Flash memory off Program operation on RAM	—	50	—	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off	—	5	80	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 0	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode	LCD drive control circuit (4) When external division resistors are used	—	5	—	µA
										LCD drive control circuit (5) When the internal voltage multiplier is used	—	11	—	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode		—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off		—	2	5.0	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off		—	13.0	—	µA
		Power-off mode	Off	Off	Off	Off	—	—	Topr = 25°C		—	0.02	0.2	µA
			Off	Off	Off	Off	—	—	Topr = 85°C		—	0.3	—	µA

Notes:
1. Vcc = 2.7 V to 4.0 V, single chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. Vcc = 3.0 V
4. VLCD = Vcc, external division resistors are used for VL4 to VL1, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open. The standard value does not include the current that flows through external division resistors.
5. The internal voltage multiplier is used, bits LVLS3 to LVLS0 in the LCR1 register = 1011b, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open.

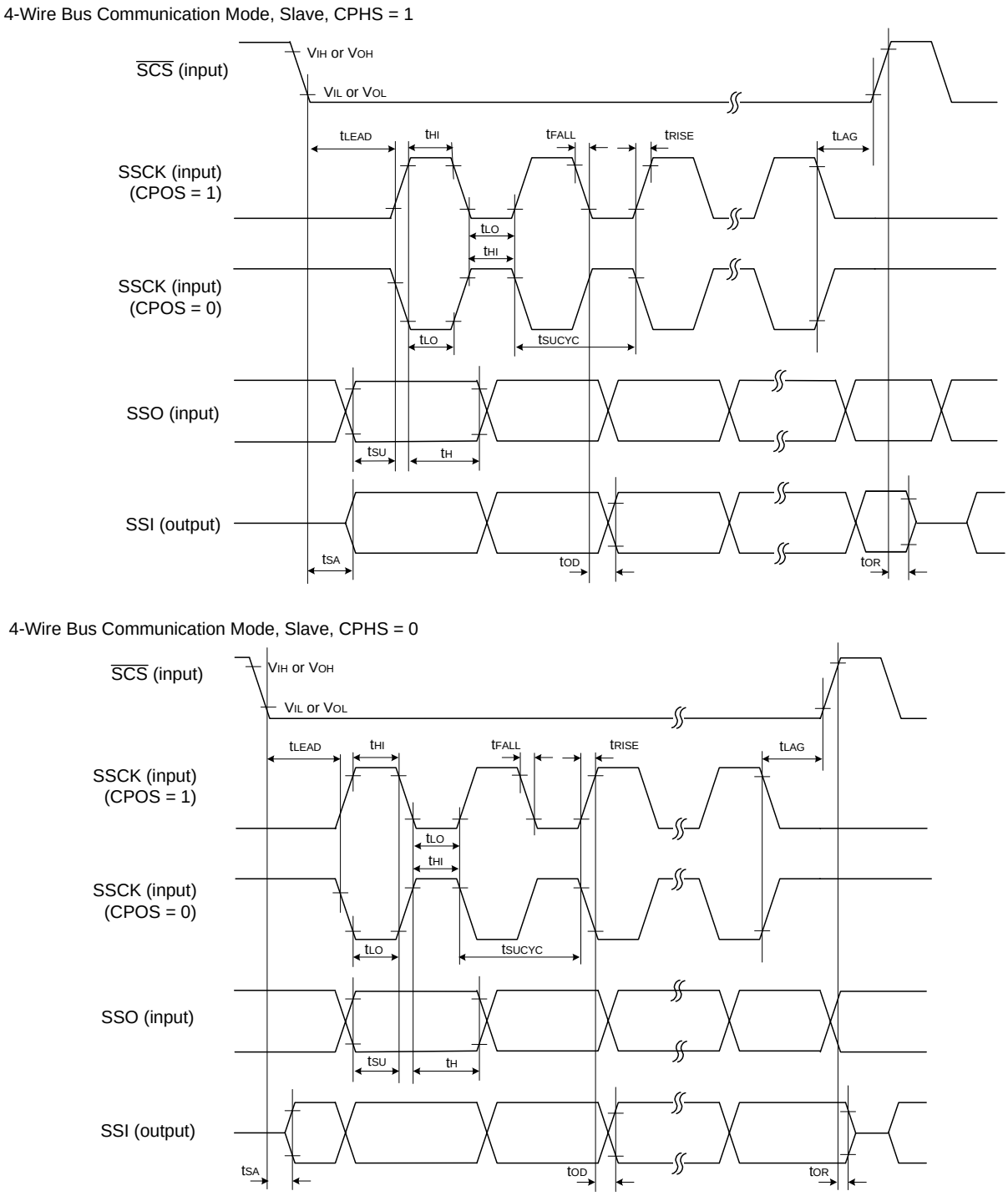
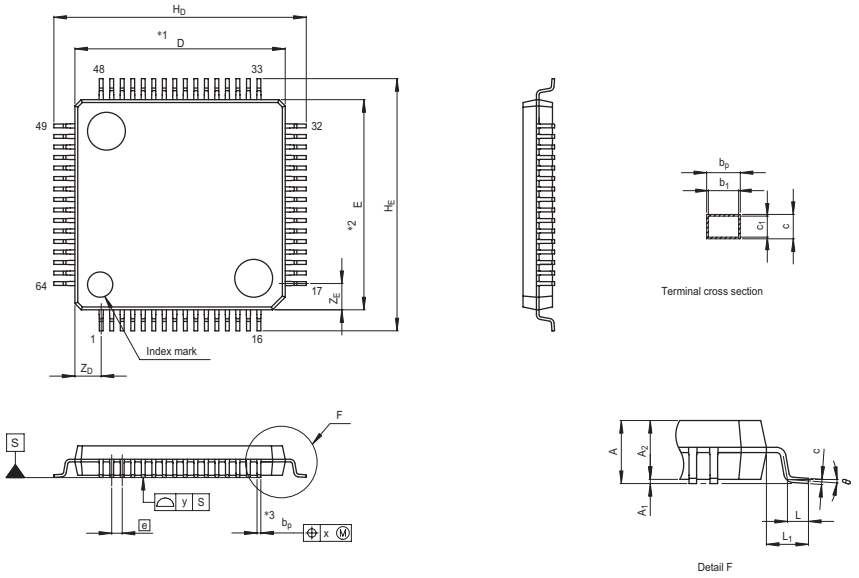


Figure 5.5 I/O Timing of Synchronous Serial Communication Unit (SSU) (Slave)

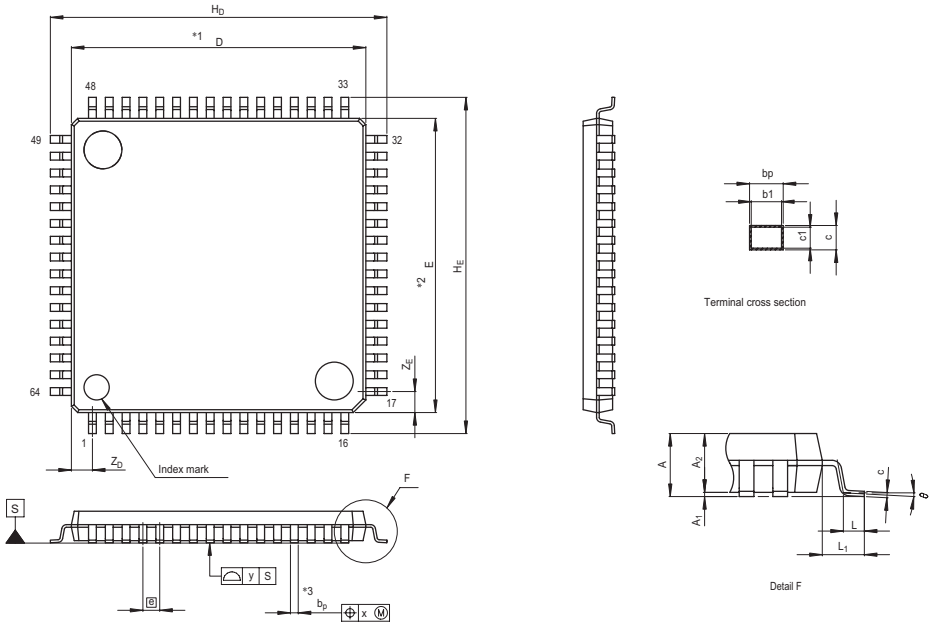
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-10x10-0.50	PLQP0064KB-A	64P6Q-A / FP-64K / FP-64KV	0.3g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	9.9	10.0	10.1
E	9.9	10.0	10.1
A_2	—	1.4	—
H_D	11.8	12.0	12.2
H_E	11.8	12.0	12.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.25	—
Z_E	—	1.25	—
L	0.35	0.5	0.65
L_1	—	1.0	—

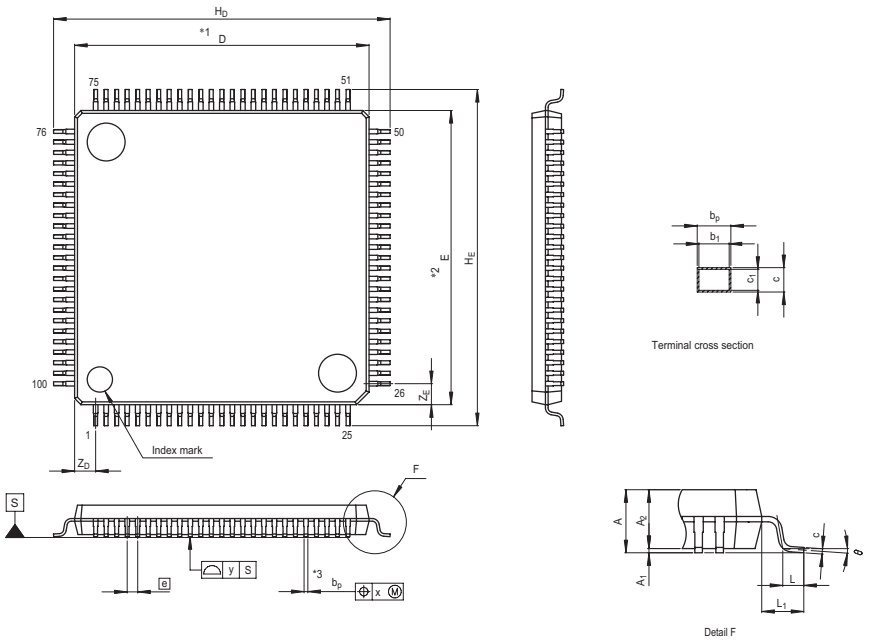
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-14x14-0.80	PLQP0064GA-A	64P6U-A/ —	0.7g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.32	0.37	0.42
b_1	—	0.35	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.8	—
x	—	—	0.20
y	—	—	0.10
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.3	0.5	0.7
L_1	—	1.0	—

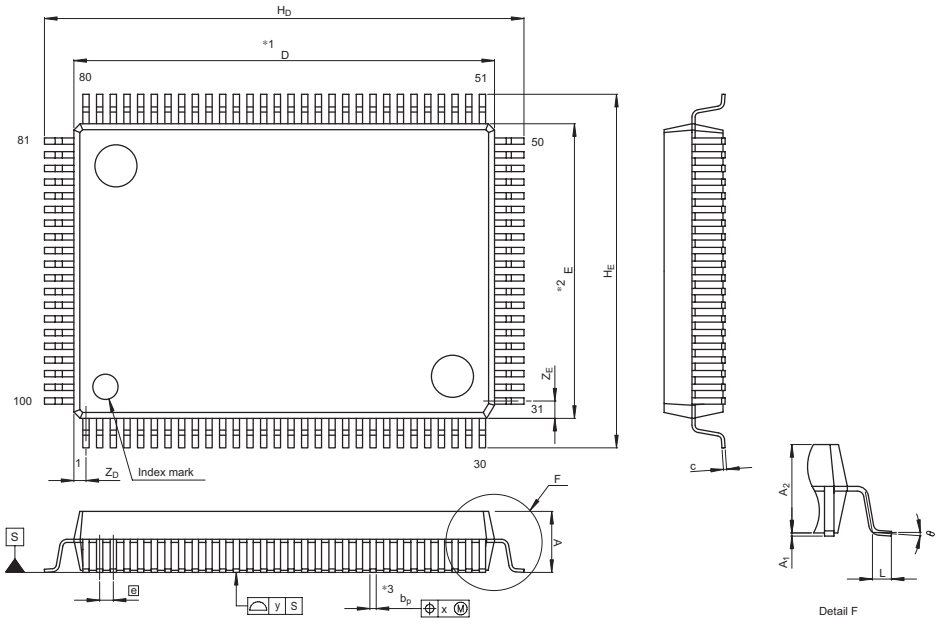
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP100-14x14-0.50	PLQP0100KB-A	100P6Q-A / FP-100U / FP-100UV	0.6g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.35	0.5	0.65
L_1	—	1.0	—

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-QFP100-14x20-0.65	PRQP0100JD-B	100P6F-A	1.8g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	19.8	20.0	20.2
E	13.8	14.0	14.2
A_2	—	2.8	—
H_D	22.5	22.8	23.1
H_E	16.5	16.8	17.1
A	—	—	3.05
A_1	0	0.1	0.2
b_p	0.25	0.3	0.4
c	0.13	0.15	0.2
θ	0°	—	10°
e	—	0.65	—
x	—	—	0.13
y	—	—	0.10
Z_D	—	0.575	—
Z_E	—	0.825	—
L	0.4	0.6	0.8

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